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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gp102t-i-ss

4.6 Interfacing Program and Data Memory Spaces

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 architecture uses a 24-bit-wide program space and a 16-bit-wide data space. The architecture is also a modified Harvard scheme, meaning that data can also be present in the program space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 architecture provides two methods by which program space can be accessed during operation:

- Using table instructions to access individual bytes, or words, anywhere in the program space
- Remapping a portion of the program space into the data space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for lookups from a large table of static data. The application can only access the lsw of the program word.

4.6.1 ADDRESSING PROGRAM SPACE

Since the address ranges for the data and program spaces are 16 and 24 bits, respectively, a method is needed to create a 23-bit or 24-bit program address from 16-bit data registers. The solution depends on the interface method to be used.

For table operations, the 8-bit Table Page (TBLPAG) register is used to define a 32K word region within the program space. This is concatenated with a 16-bit EA to arrive at a full 24-bit program space address. In this format, the MSb of TBLPAG is used to determine if the operation occurs in the user memory (TBLPAG<7> = 0) or the configuration memory (TBLPAG<7> = 1).

For remapping operations, the 8-bit Program Space Visibility (PSVPAG) register is used to define a 16K word page in the program space. When the MSb of the EA is '1', PSVPAG is concatenated with the lower 15 bits of the EA to form a 23-bit program space address. Unlike table operations, this limits remapping operations strictly to the user memory area.

Table 4-42 and Figure 4-9 show how the program EA is created for table operations and remapping accesses from the data EA.

TABLE 4-42: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		
Program Space Visibility (Block Remap/Read)	User	0	PSVPAG<7:0>		Data EA<14:0>(1)	
		0	xxxx xxxx		xxx xxxx xxxx xxxx	

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.

6.2 System Reset

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family of devices have two types of Reset:

- Cold Reset
- Warm Reset

A Cold Reset is the result of a POR or a BOR. On a Cold Reset, the FNOSC<2:0> Configuration bits in the FOSCSEL Configuration register selects the device clock source.

A Warm Reset is the result of all other Reset sources, including the RESET instruction. On Warm Reset, the device will continue to operate from the current clock source as indicated by the Current Oscillator Selection (COSC<2:0>) bits in the Oscillator Control (OSCCON<14:12>) register.

The device is kept in a Reset state until the system power supplies have stabilized at appropriate levels and the oscillator clock is ready. The sequence in which this occurs is shown in Figure 6-2.

TABLE 6-1: OSCILLATOR DELAY

Oscillator Mode	Oscillator Start-up Delay	Oscillator Start-up Timer	PLL Lock Time	Total Delay
FRC, FRCDIV16, FRCDIVN	TOSCD(1)	—	—	TOSCD
FRCPLL	TOSCD(1)	—	TLOCK(3)	TOSCD(1) + TLOCK(3)
MS	TOSCD(1)	TOST(2)	—	TOSCD(1) + TOST(2)
HS	TOSCD(1)	TOST(2)	—	TOSCD(1) + TOST(2)
EC	—	—	—	—
MSPLL	TOSCD(1)	TOST(2)	TLOCK(3)	TOSCD(1) + TOST(2) + TLOCK(3)
ECPLL	—	—	TLOCK(3)	TLOCK(3)
SOSC	TOSCD(1)	TOST(2)	—	TOSCD(1) + TOST(2)
LPRC	TOSCD(1)	—	—	TOSCD(1)

Note 1: TOSCD = Oscillator Start-up Delay (1.1 μs max. for FRC, 70 μs max. for LPRC). Crystal oscillator start-up times vary with crystal characteristics, load capacitance, etc.

2: TOST = Oscillator Start-up Timer Delay (1024 oscillator clock period). For example, TOST = 102.4 μs for a 10 MHz crystal and TOST = 32 ms for a 32 kHz crystal.

3: TLOCK = PLL Lock time (1.5 ms nominal) if PLL is enabled.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Arithmetic Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **MATHERR:** Arithmetic Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

8.1.3 PLL CONFIGURATION

The primary oscillator and internal FRC oscillator can optionally use an on-chip, 4x PLL to obtain higher speeds of operation.

For example, suppose an 8 MHz crystal is being used with the selected oscillator mode of MS with PLL. This provides a FOSC of 8 MHz * 4 = 32 MHz. The resultant device operating speed is 32/2 = 16 MIPS.

EQUATION 8-2: MS WITH PLL MODE EXAMPLE

$$F_{CY} = \frac{F_{OSC}}{2} = \frac{1}{2}(8000000 \bullet 4) = 16 \text{ MIPS}$$

TABLE 8-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Note
Fast RC Oscillator with Divide-by-n (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Secondary (Timer1) Oscillator (SOSC)	Secondary	xx	100	**1**
Primary Oscillator (MS) with PLL (MSPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (MS)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator (FRC) with Divide-by-n and PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

10.4.3 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices include three features to prevent alterations to the peripheral map:

- Control register lock sequence
- Continuous state monitoring
- Configuration bit pin select lock

10.4.3.1 Control Register Lock

Under normal operation, writes to the RPINRx and RPORx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK bit (OSCCON<6>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear IOLOCK, a specific command sequence must be executed:

1. Write 0x46 to OSCCON<7:0>.
2. Write 0x57 to OSCCON<7:0>.
3. Clear (or set) IOLOCK as a single operation.

Note: MPLAB® C30 provides built-in C language functions for unlocking the OSCCON register:

```
__builtin_write_OSCCONL(value)
__builtin_write_OSCCONH(value)
```

See MPLAB IDE Help for more information.

Unlike the similar sequence with the oscillator's LOCK bit, IOLOCK remains in one state until changed. This allows all of the Peripheral Pin Selects to be configured with a single unlock sequence followed by an update to all control registers, then locked with a second lock sequence.

10.4.3.2 Continuous State Monitoring

In addition to being protected from direct writes, the contents of the RPINRx and RPORx registers are constantly monitored in hardware by shadow registers. If an unexpected change in any of the registers occurs (such as cell disturbances caused by ESD or other external events), a Configuration Mismatch Reset will be triggered.

10.4.3.3 Configuration Bit Pin Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPINRx and RPORx registers. The IOL1WAY (FOSC<5>) Configuration bit blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure will not execute and the Peripheral Pin Select Control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session. Programming IOL1WAY allows user applications unlimited access (with the proper use of the unlock sequence) to the Peripheral Pin Select registers.

REGISTER 15-10: PxFLTBCON: PWMx FAULT B CONTROL REGISTER(1,2,3,4)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	FBOV3H	FBOV3L	FBOV2H	FBOV2L	FBOV1H	FBOV1L
bit 15							bit 8

R/W-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
FLTBM	—	—	—	—	FBEN3	FBEN2	FBEN1
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **FBOV<3:1>H:FBOV<3:1>L:** Fault Input B PWMx Override Value bits
1 = The PWMx output pin is driven active on an external Fault input event
0 = The PWMx output pin is driven inactive on an external Fault input event

bit 7 **FLTBM:** Fault B Mode bit
1 = The Fault B input pin functions in the Cycle-by-Cycle mode
0 = The Fault B input pin latches all control pins to the programmed states in PxFLTBCON<13:8>

bit 6-3 **Unimplemented:** Read as ‘0’

bit 2 **FBEN3:** Fault Input B Enable bit
1 = PWMxH3/PWMxL3 pin pair is controlled by Fault Input B
0 = PWMxH3/PWMxL3 pin pair is not controlled by Fault Input B

bit 1 **FBEN2:** Fault Input B Enable bit
1 = PWMxH2/PWMxL2 pin pair is controlled by Fault Input B
0 = PWMxH2/PWMxL2 pin pair is not controlled by Fault Input B

bit 0 **FBEN1:** Fault Input B Enable bit
1 = PWMxH1/PWMxL1 pin pair is controlled by Fault Input B
0 = PWMxH1/PWMxL1 pin pair is not controlled by Fault Input B

Note 1: Comparator outputs are not internally connected to the PWM Fault control logic. If using the comparator modules for Fault generation, the user must externally connect the desired comparator output pin to the dedicated $\overline{\text{FLTA1}}$ or $\overline{\text{FLTB1}}$ input pin.

2: Refer to Table 15-1 for $\overline{\text{FLTB1}}$ implementation details.

3: The PxFLTACON register is a write-protected register. Refer to **Section 15.3 “Write-Protected Registers”** for more information on the unlock sequence.

4: During any Reset event, $\overline{\text{FLTB1}}$ is enabled by default and must be cleared as described in **Section 15.2 “PWM Faults”**.

18.3 UART Control Registers

REGISTER 18-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by the UEN<1:0> bits
- 0 = UARTx is disabled; all UARTx pins are controlled by port latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
- 1 = Discontinues module operation when device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** UARTx Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Pin Enable bits
- 11 = UxTX, UxRX and BCLK pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by port latches
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLK pins are controlled by port latches

bit 7 **WAKE:** Wake-up on Start bit Detect During Sleep Mode Enable bit
- 1 = UARTx will continue to sample the UxRX pin; interrupt is generated on falling edge, bit is cleared in hardware on following rising edge
- 0 = No wake-up is enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Enables Loopback mode
- 0 = Loopback mode is disabled

bit 5 **ABAUD:** Auto-Baud Enable bit
- 1 = Enables baud rate measurement on the next character – requires reception of a Sync field (55h) before other data; cleared in hardware upon completion
- 0 = Baud rate measurement is disabled or completed

Note 1: Refer to **"UART"** (DS70188) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is available for 16x BRG mode (BRGH = 0) only.

REGISTER 18-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 4 **URXINV:** UARTx Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
1 = BRG generates 4 clocks per bit period (4x baud clock, High-Speed mode)
0 = BRG generates 16 clocks per bit period (16x baud clock, Standard mode)

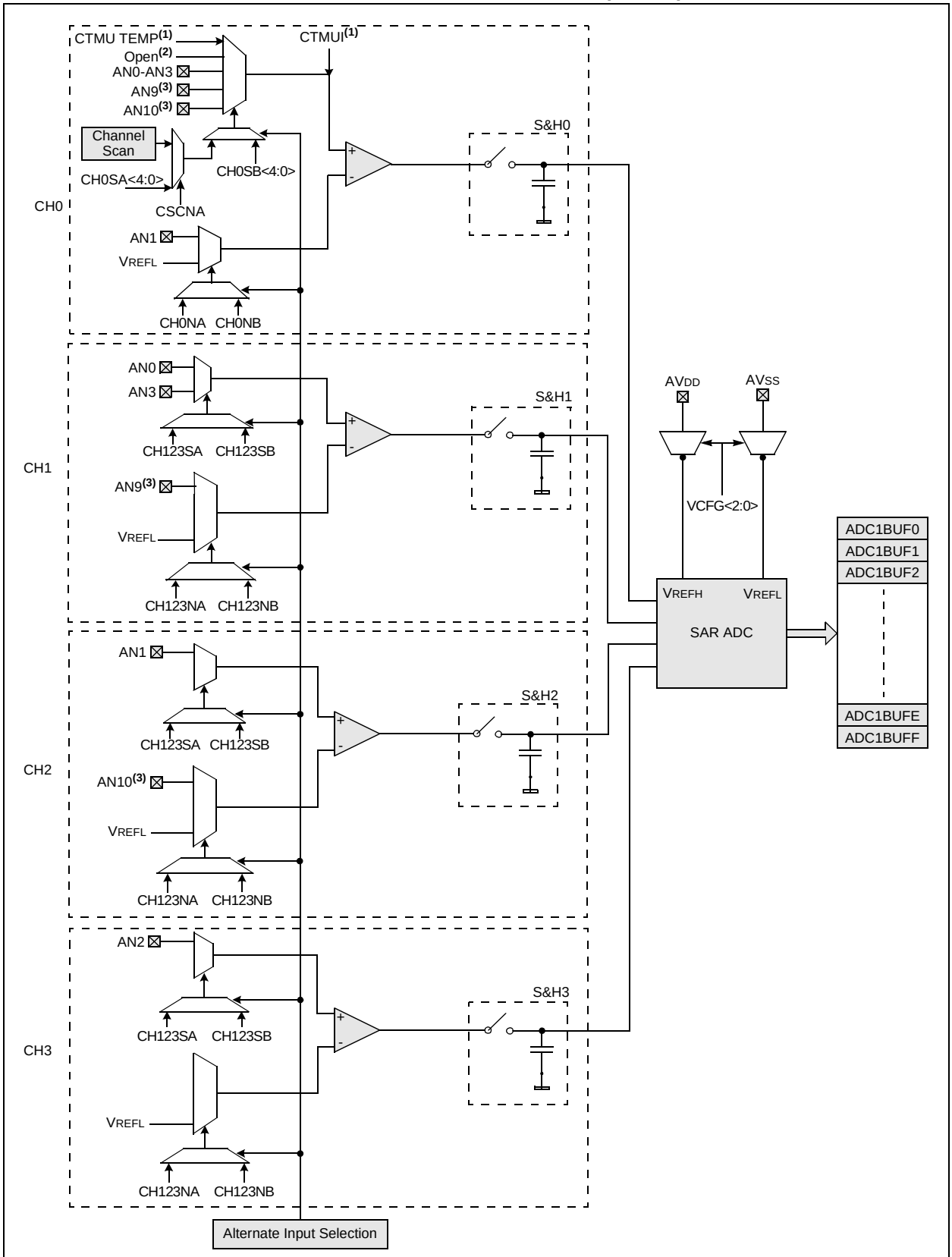
bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Bit Selection bit
1 = Two Stop bits
0 = One Stop bit

Note 1: Refer to **"UART"** (DS70188) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is available for 16x BRG mode (BRGH = 0) only.

FIGURE 19-1: ADC1 BLOCK DIAGRAM FOR dsPIC33FJXX(GP/MC)101 DEVICES



Note 1: Internally connected to the CTMU module.
2: This selection is only used with CTMU capacitive and time measurement.
3: This pin is available in dsPIC33FJ32(GP/MC)101 devices only.

19.5 ADC Control Registers

REGISTER 19-1: AD1CON1: ADC1 CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
ADON	—	ADSIDL	—	—	—	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0, HC, HS	R/C-0, HC, HS
SSRC2	SSRC1	SSRC0	—	SIMSAM	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** ADC1 Operating Mode bit
1 = ADC1 module is operating
0 = ADC1 is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** ADC1 Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-10 **Unimplemented:** Read as '0'

bit 9-8 **FORM<1:0>:** Data Output Format bits
11 = Signed fractional (DOUT = sddd dddd dd00 0000, where s = .NOT.d<9>)
10 = Fractional (DOUT = dddd dddd dd00 0000)
01 = Signed integer (DOUT = ssss sssd dddd dddd, where s = .NOT.d<9>)
00 = Integer (DOUT = 0000 00dd dddd dddd)

bit 7-5 **SSRC<2:0>:** Sample Clock Source Select bits
111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = CTMU
101 = Reserved
100 = Reserved
011 = Motor control PWM interval ends sampling and starts conversion(1)
010 = GP Timer3 compare ends sampling and starts conversion
001 = Active transition on INT0 pin ends sampling and starts conversion
000 = Clearing SAMP bit ends sampling and starts conversion

bit 4 **Unimplemented:** Read as '0'

bit 3 **SIMSAM:** Simultaneous Sample Select bit (applicable only when CHPS<1:0> = 01 or 1x)
1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x) or samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)
0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADC1 Sample Auto-Start bit
1 = Sampling begins immediately after last conversion; SAMP bit is auto-set
0 = Sampling begins when the SAMP bit is set

Note 1: This feature is available in dsPIC33FJ(16/32)MC10X devices only.

23.0 SPECIAL FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Programming and Diagnostics"** (DS70207) and **"Device Configuration"** (DS70194) in the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

23.1 Configuration Bits

The Configuration Shadow register bits can be configured (read as '0') or left unprogrammed (read as '1') to select various device configurations. These read-only bits are mapped starting at program memory location, 0xF80000. A detailed explanation of the various bit functions is provided in Table 23-4.

Note that address, 0xF80000, is beyond the user program memory space and belongs to the configuration memory space (0x800000-0xFFFFFF), which can only be accessed using Table Reads.

In dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in the two words at the top of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 23-2. These are packed representations of the actual device Configuration bits, whose actual locations are distributed among several locations in configuration space. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Word for configuration data. This is to make certain that program code is not stored in this address when the code is compiled.

The upper byte of all Flash Configuration Words in program memory should always be '1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration Words, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Shadow register map is shown in Table 23-1.

TABLE 23-1: CONFIGURATION SHADOW REGISTER MAP

File Name	Addr.	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FGS	F80004	—	—	—	—	—	—	GCP	GWRP
FOSCSEL	F80006	IESO	PWMLOCK(1)	—	WDTWIN1	WDTWIN0	FNOSC2	FNOSC1	FNOSC0
FOSC	F80008	FCKSM1	FCKSM0	IOL1WAY	—	—	OSCIOFNC	POSCMD1	POSCMD0
FWDT	F8000A	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST3	WDTPOST2	WDTPOST1	WDTPOST0
FPOR	F8000C	PWMPIN(1)	HPOL(1)	LPOL(1)	ALTI2C1	—	—	—	—
FICD	F8000E	Reserved(2)	—	Reserved(3)	Reserved(3)	—	—	ICS1	ICS0

Legend: — = unimplemented, read as '1'.
Note 1: These bits are available in dsPIC33FJ(16/32)MC10X devices only.
2: This bit is reserved for use by development tools.
3: These bits are reserved, program as '0'.

The Configuration Flash Word maps are shown in Table 23-2 and Table 23-3.

TABLE 23-2: CONFIGURATION FLASH WORDS FOR dsPIC33FJ16(GP/MC)10X DEVICES(1)

File Name	Addr.	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CONFIG2	002BFC	—	IESO	PWMLOCK(2)	PWMPIN(2)	WDTWIN1	WDTWIN0	FNOSC2	FNOSC1	FNOSC0	FCKSM1	FCKSM0	OSCIOFNC(5)	IOL1WAY	LPOL(2)	ALTI2C1	POSCMD1	POSCMD0
CONFIG1	002BFE	—	Reserved(3)	Reserved(3)	GCP	GWRP	Reserved(4)	HPOL(2)	ICS1	ICS0	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST3	WDTPOST2	WDTPOST1	WDTPOST0

Legend: — = unimplemented, read as '1'.
Note 1: During a Power-on Reset (POR), the contents of these Flash locations are transferred to the Configuration Shadow registers.
2: These bits are reserved in dsPIC33FJ16GP10X devices and read as '1'.
3: These bits are reserved, program as '0'.
4: This bit is reserved for use by development tools and must be programmed as '1'.
5: This bit is programmed to '0' during final tests in the factory.

TABLE 23-3: CONFIGURATION FLASH WORDS FOR dsPIC33FJ32(GP/MC)10X DEVICES(1)

File Name	Addr.	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CONFIG2	0057FC	—	IESO	PWMLOCK(2)	PWMPIN(2)	WDTWIN1	WDTWIN0	FNOSC2	FNOSC1	FNOSC0	FCKSM1	FCKSM0	OSCIOFNC(5)	IOL1WAY	LPOL(2)	ALTI2C1	POSCMD1	POSCMD0
CONFIG1	0057FE	—	Reserved(3)	Reserved(3)	GCP	GWRP	Reserved(4)	HPOL(2)	ICS1	ICS0	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST3	WDTPOST2	WDTPOST1	WDTPOST0

Legend: — = unimplemented, read as '1'.
Note 1: During a Power-on Reset (POR), the contents of these Flash locations are transferred to the Configuration Shadow registers.
2: These bits are reserved in dsPIC33FJ32GP10X devices and read as '1'.
3: These bits are reserved, program as '0'.
4: This bit is reserved for use by development tools and must be programmed as '1'.
5: This bit is programmed to '0' during final tests in the factory.

23.2 On-Chip Voltage Regulator

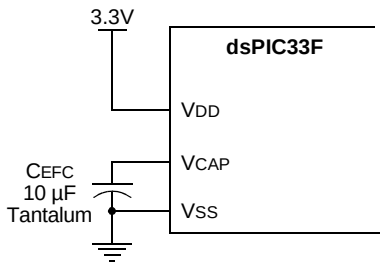
All of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 23-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 26-14 located in **Section 26.1 "DC Characteristics"**.

Note:	It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 μs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 23-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 26-14 located in **Section 26.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

23.3 BOR: Brown-out Reset

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an Oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
66	RRNC	RRNC	f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
67	SAC	SAC	Acc,#Slit4,Wdo	Store Accumulator	1	1	None
		SAC.R	Acc,#Slit4,Wdo	Store Rounded Accumulator	1	1	None
68	SE	SE	Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
69	SETM	SETM	f	f = 0xFFFF	1	1	None
		SETM	WREG	WREG = 0xFFFF	1	1	None
		SETM	Ws	Ws = 0xFFFF	1	1	None
70	SFTAC	SFTAC	Acc,Wn	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC	Acc,#Slit6	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB
71	SL	SL	f	f = Left Shift f	1	1	C,N,OV,Z
		SL	f,WREG	WREG = Left Shift f	1	1	C,N,OV,Z
		SL	Ws,Wd	Wd = Left Shift Ws	1	1	C,N,OV,Z
		SL	Wb,Wns,Wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z
		SL	Wb,#lit5,Wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z
72	SUB	SUB	Acc	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		SUB	f	f = f – WREG	1	1	C,DC,N,OV,Z
		SUB	f,WREG	WREG = f – WREG	1	1	C,DC,N,OV,Z
		SUB	#lit10,Wn	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		SUB	Wb,Ws,Wd	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		SUB	Wb,#lit5,Wd	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
73	SUBB	SUBB	f	f = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	f,WREG	WREG = f – WREG – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	#lit10,Wn	Wn = Wn – lit10 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	Wb,Ws,Wd	Wd = Wb – Ws – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBB	Wb,#lit5,Wd	Wd = Wb – lit5 – ($\overline{C}$)	1	1	C,DC,N,OV,Z
74	SUBR	SUBR	f	f = WREG – f	1	1	C,DC,N,OV,Z
		SUBR	f,WREG	WREG = WREG – f	1	1	C,DC,N,OV,Z
		SUBR	Wb,Ws,Wd	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		SUBR	Wb,#lit5,Wd	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
75	SUBBR	SUBBR	f	f = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR	f,WREG	WREG = WREG – f – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR	Wb,Ws,Wd	Wd = Ws – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
		SUBBR	Wb,#lit5,Wd	Wd = lit5 – Wb – ($\overline{C}$)	1	1	C,DC,N,OV,Z
76	SWAP	SWAP.b	Wn	Wn = nibble swap Wn	1	1	None
		SWAP	Wn	Wn = byte swap Wn	1	1	None
77	TBLRDH	TBLRDH	Ws,Wd	Read Prog<23:16> to Wd<7:0>	1	2	None
78	TBLRDL	TBLRDL	Ws,Wd	Read Prog<15:0> to Wd	1	2	None
79	TBLWTH	TBLWTH	Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
80	TBLWTL	TBLWTL	Ws,Wd	Write Ws to Prog<15:0>	1	2	None
81	ULNK	ULNK		Unlink Frame Pointer	1	1	None
82	XOR	XOR	f	f = f .XOR. WREG	1	1	N,Z
		XOR	f,WREG	WREG = f .XOR. WREG	1	1	N,Z
		XOR	#lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N,Z
		XOR	Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N,Z
		XOR	Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N,Z
83	ZE	ZE	Ws,Wnd	Wnd = Zero-extend Ws	1	1	C,Z,N

26.2 AC Characteristics and Timing Parameters

This section defines dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family AC characteristics and timing parameters.

TABLE 26-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 26.1 "DC Characteristics"**.

FIGURE 26-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

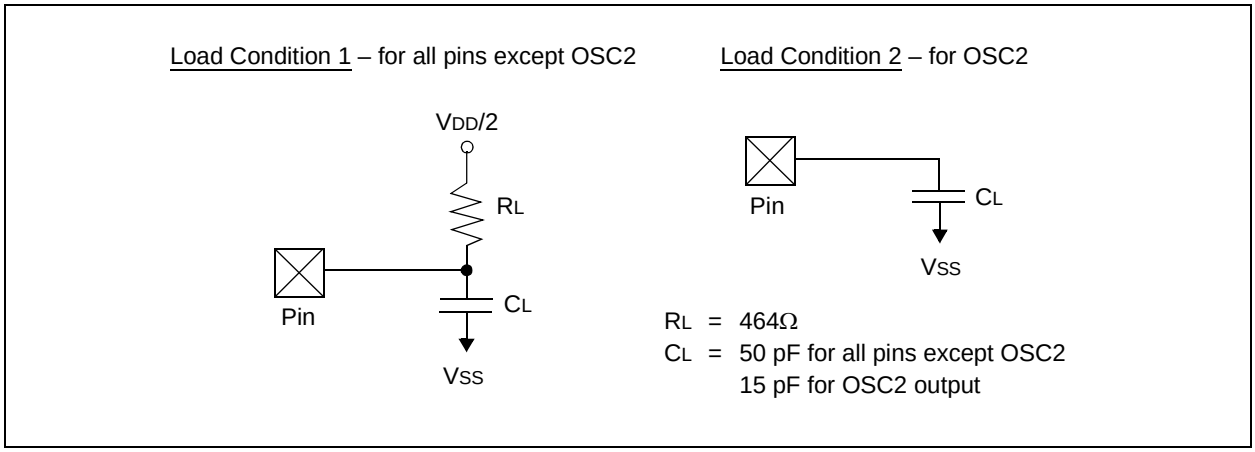
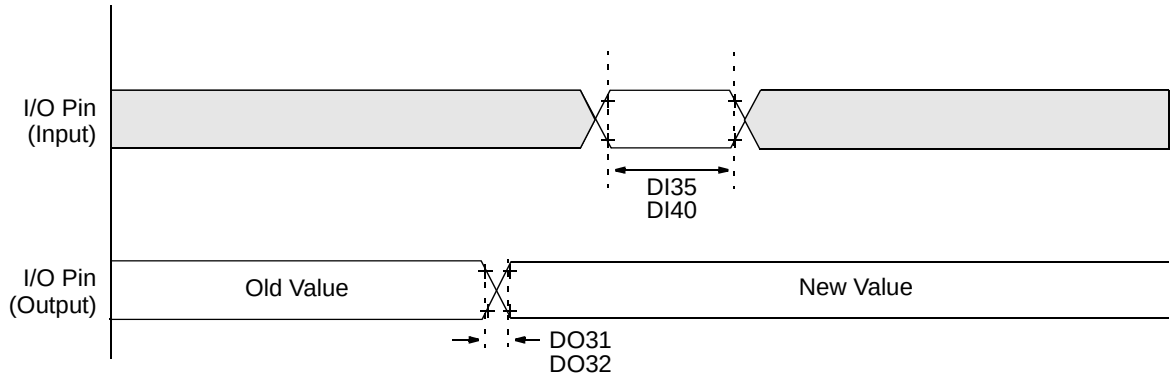


TABLE 26-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
DO50	COSC2	OSC2/SOSC2 Pin	—	—	15	pF	In MS and HS modes when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C™ mode

FIGURE 26-3: CLKO AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-20: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	
DO32	TIOF	Port Output Fall Time	—	10	25	ns	
DI35	TINP	INTx Pin High or Low Time (input)	25	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 26-49: 10-BIT ADC CONVERSION TIMING REQUIREMENTS

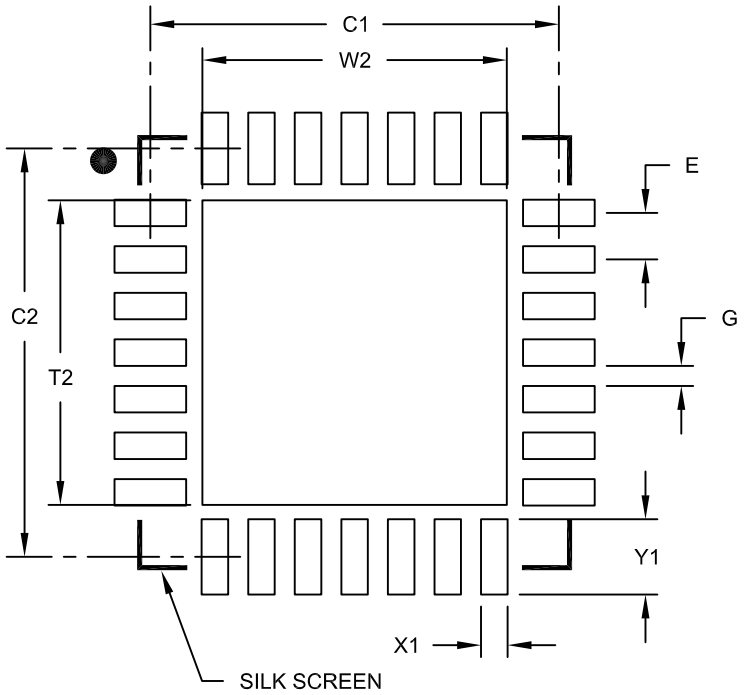
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters(2)							
AD50	TAD	ADC Clock Period	76	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rates							
AD55	tCONV	Conversion Time	—	12 TAD	—	—	
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	
AD57	TSAMP	Sample Time	2.0 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(1)	2.0 TAD	—	3.0 TAD	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(1)	2.0 TAD	—	3.0 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(1)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(1)	—	—	20	μs	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

Notes:

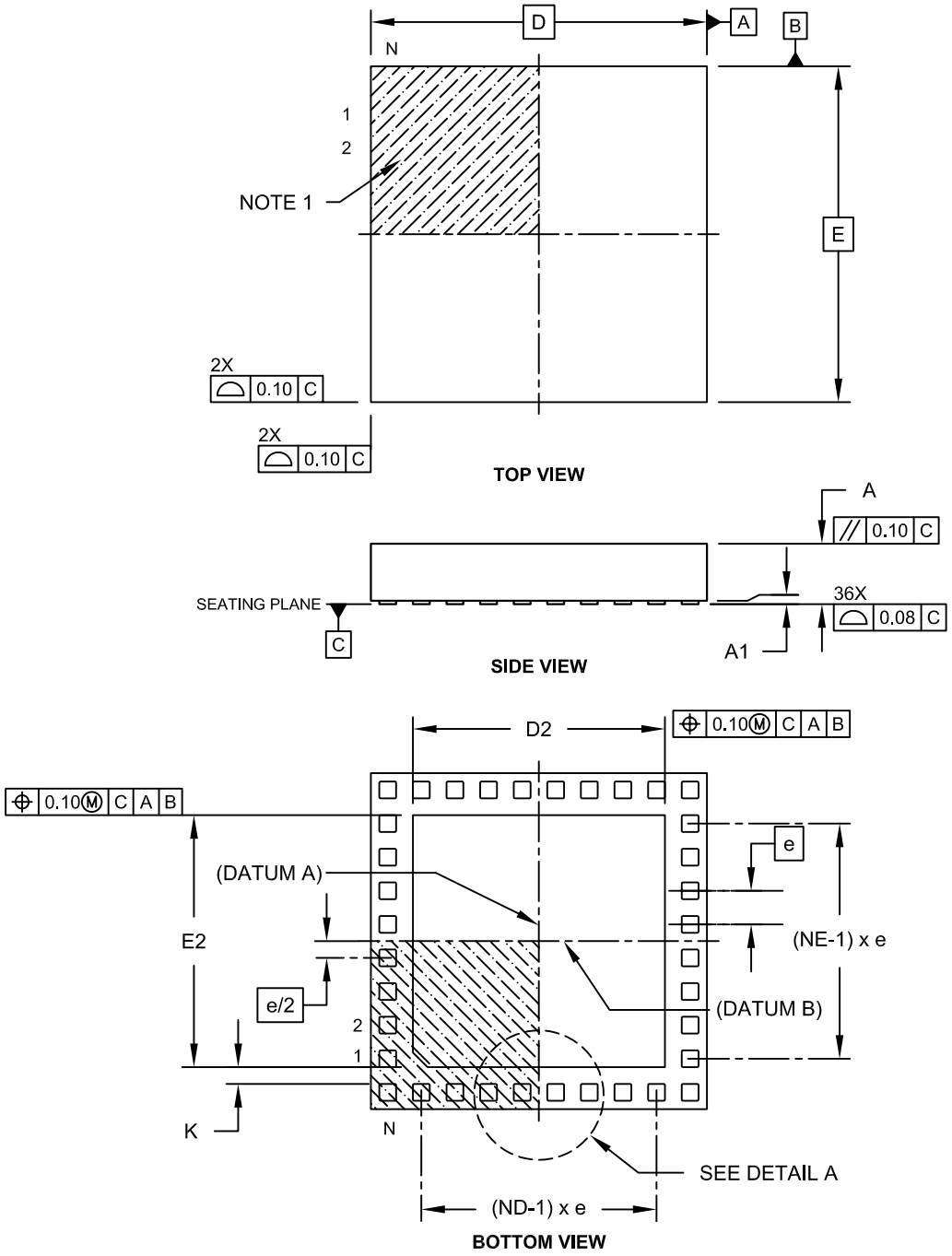
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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